



# BW21-CBV Specification

Version V1.0.0

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## 1. Product Overview

BW 21-CBV is a dual-frequency Wi-Fi + BLE camera SoC module developed by Shenzhen Ai-Thinker Technology Co., Ltd. based on RTL8735B series chips, which supports dual-frequency (2.4 GHz or 5 GHz)802.11a/b/g/n WLAN protocol and BLE 5.1 protocol. BW 21-CBV integrates ARM v8M MCU (500 MHz and 2.23 DMIP S/MHz), WLAN MAC, WLAN baseband with 1T1R support, Bluetooth MAC, RF, audio codec, ISP, and H264 / H265 encoder.

The BW 21-CBV module has rich peripheral interfaces, including UART / GPIO / ADC / PWM / IIC / IIS / SPI / SDIO / SWD / EPHY / Audio / MI C/M IPI / USB et al. It can be widely used in the Internet of Things (IoT), intelligent audio and video devices, smart home and other fields.

## 1.1. Characteristic

- Support 802.11a/b/g/n protocol
- Support for 802.11e QoS enhancement (WMM)
- Support for dual-frequency 2.4GHz or 5GHz
- Supports the HT 20 / HT 40 mode
- Support for the BLE 5.1 protocol
- Support for a LE secure connection
- Support for the LE scattering net
- Support LE 1 master / 1 slave
- LE data length extension
- Support for link layer privacy
- Support for a hardware encryption engine
- Real-M500 (TM9) clock frequency up to 500 MHz
- Abundant interfaces, with 58 flexible and compatible IO ports
- YUY2 input and 12-bit Bayer mode input for 8-bit CMOS sensor
- Support for MIPI CSI-2 four data channels
- Support for MCM embedded 64MB / 128MB DDR2 memory
- Support for short distance low power Tx / Rx applications
- Wi-Fi and Bluetooth share the same antenna
- Support for Arduino development

## 2. Main Parameters

**Table 1 Description of the main parameters**

<b>Model</b>	BW21-CBV
<b>Package</b>	SMD-90
<b>Size</b>	27.5*20*3.2(±0.2)MM
<b>Antenna</b>	I-PEX (1 generation)
<b>Frequency</b>	2400~2483.5MHz or 5180~5825MHz
<b>Operating temperature</b>	-40 °C~85 °C
<b>Storage temperature</b>	-40 °C~125 °C, <90%RH
<b>Power supply</b>	Power supply voltage is 3.135V~3.465V, the typical value is 3.3V, and the power supply current is > 700 mA
<b>Interface</b>	UART/GPIO/ADC/PWM/IIC/IIS/SPI/SDIO/SWD/EPHY/ Audio/MIC/MIPI/USB
<b>IO</b>	Default 58
<b>UART rate</b>	Default 115200bps
<b>Bluetooth</b>	BLE 5.1
<b>SPI Flash</b>	Default 16MByte

### 2.1. Static electricity requirement

BW 21-CBV module is electrostatic sensitive device, which requires special ESD precautions, and usually ESD protective devices should be added in use. Proper ESD handling and packaging must be used during the transportation, operation, and use of the BW21-CBV module. Do not touch the module by hand or use non-antistatic iron to damage the module.



**Figure 2 ESD Antic-static diagram**

## 2.2. Electrical Characteristics

**Table 2 Electrical characteristics table**

<b>Parameters</b>		<b>Condition</b>	<b>Min.</b>	<b>Typical value</b>	<b>Max.</b>	<b>Unit</b>
Voltage Supply	VDD_DD R (DDR2)		1.71	1.8	1.89	V
	VDD3		3.135	3.3	3.465	V
	5VDD		4.75	5	5.25	V
I/O	VIL	-	-	-	0.8	V
	VIH	-	2.0	-	-	V
	VOL	-	2.4	-	-	V
	VOH	-	-	-	0.4	V

## 2.3. Wi-Fi RF Performance

**Table 3 Wi-Fi RF performance table**

<b>Description</b>		<b>Typical value</b>			<b>Unit</b>
Frequency range		2400~2483.5 和 5180~5825			MHz
<b>Output Power</b>					
<b>Mode</b>		<b>Min.</b>	<b>Typical</b>	<b>Max.</b>	<b>Unit</b>
11a mode, PA output power		-	17	-	dBm
11b mode, PA output power		-	19	-	dBm
11g mode, PA output power		-	18	-	dBm
11n mode, PA output power		-	17	-	dBm
<b>Receive Sensitivity</b>					
<b>Mode</b>		<b>Min.</b>	<b>Typical</b>	<b>Max.</b>	<b>Unit</b>
11b, 1Mbps		-	-98	-	dBm
11b, 11Mbps		-	-91	-	dBm
11a/g, 6Mbps		-	-97	-	dBm
11a/g, 54Mbps		-	-78	-	dBm
HT20 (MCS0)		-	-96	-	dBm
HT20 (MCS7)		-	-76	-	dBm

HT40 (MCS0)	-	-93	-	dBm
HT40 (MCS7)	-	-73	-	dBm

## 2.4. BLE RF Performance

**Table 4 BLE RF performance table**

Description	Typical value			Unit
Frequency range	2400~2483.5			MHz
<b>Output Power</b>				
Rate Mode	Min.	Typical	Max.	Unit
1Mbps	-	8	-	dBm
2Mbps	-	8	-	dBm
<b>Receive Sensitivity</b>				
Rate Mode	Min.	Typical	Max.	Unit
1Mbps @30.8%PER	-	-98	-	dBm
2Mbps @30.8%PER	-	-96	-	dBm

## 2.5. Power

The following power consumption data are based on the 3.3V power supply and the ambient temperature of 25°C.

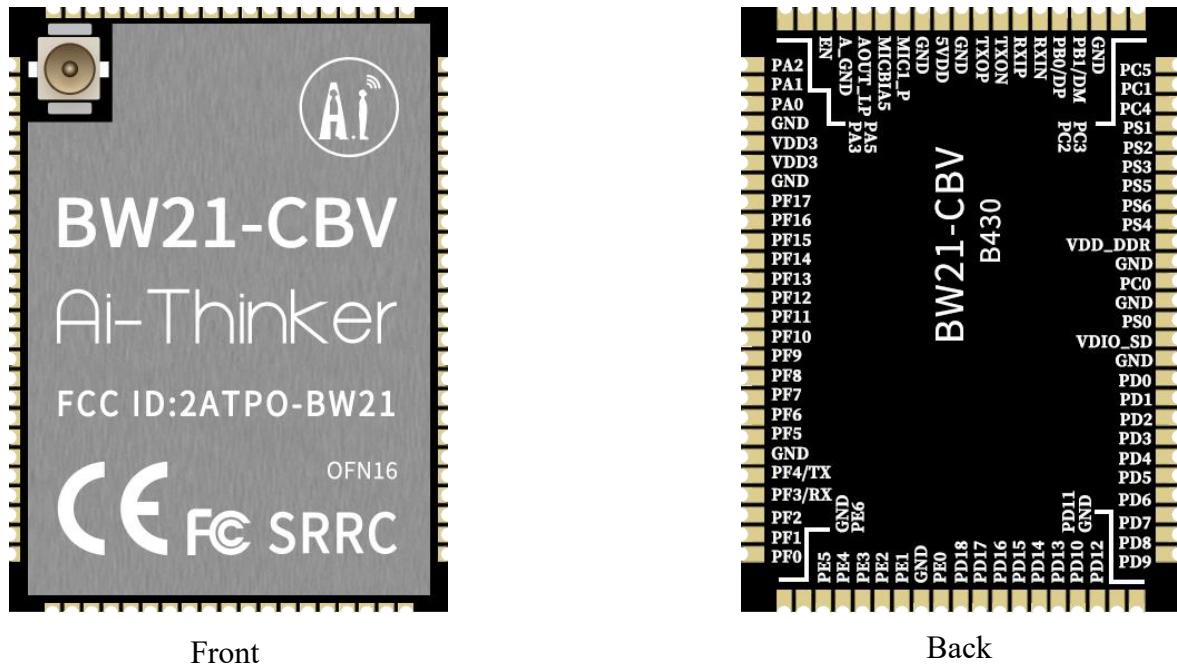
The POUT power for all transmission modes is measured at the antenna interface.

All transmission data are measured in continuous transmission mode.

**Table 5 Power consumption**

Mode	Min.	AVG	Max.	Unit
Tx 802.11b, 11Mbps, POUT=+21dBm	-	615	-	mA
Tx 802.11g, 54Mbps, POUT =+19dBm	-	398	-	mA
Txc 802.11n, MCS7, POUT =+18dBm	-	369	-	mA
Rx 802.11b	-	50	-	mA
Rx 802.11g	-	50	-	mA
Rx 802.11n	-	50	-	mA

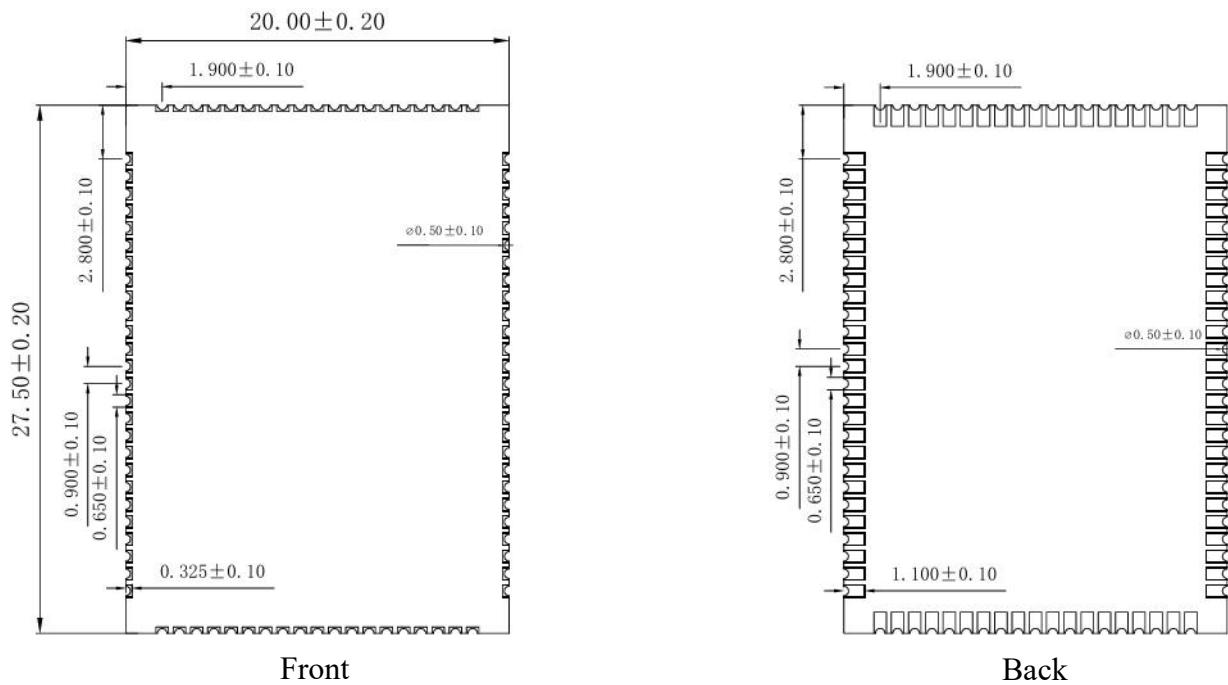
### 3. Appearance Dimensions



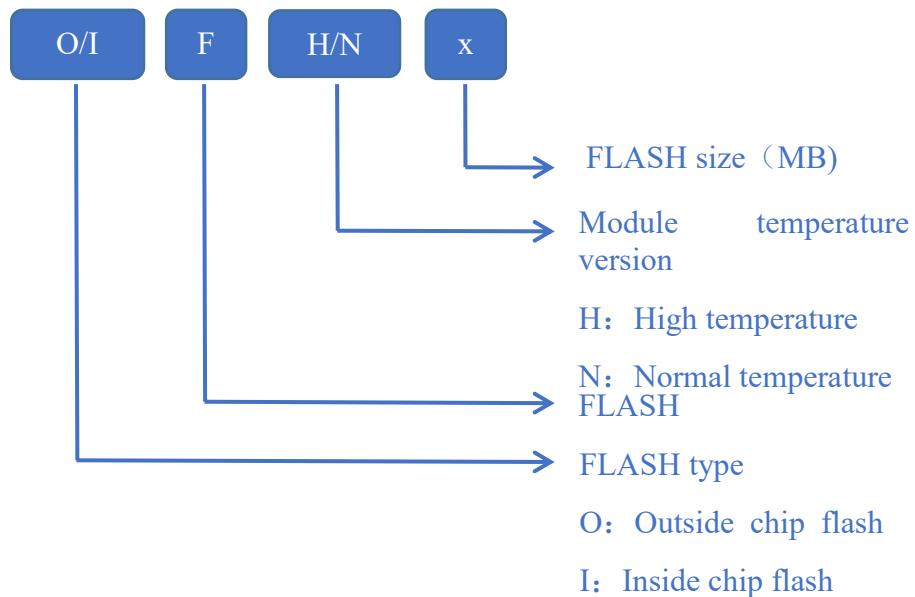
Front

Back

**Figure 3 Appearance diagram (rendering diagram is for reference only, subject to physical objects)**



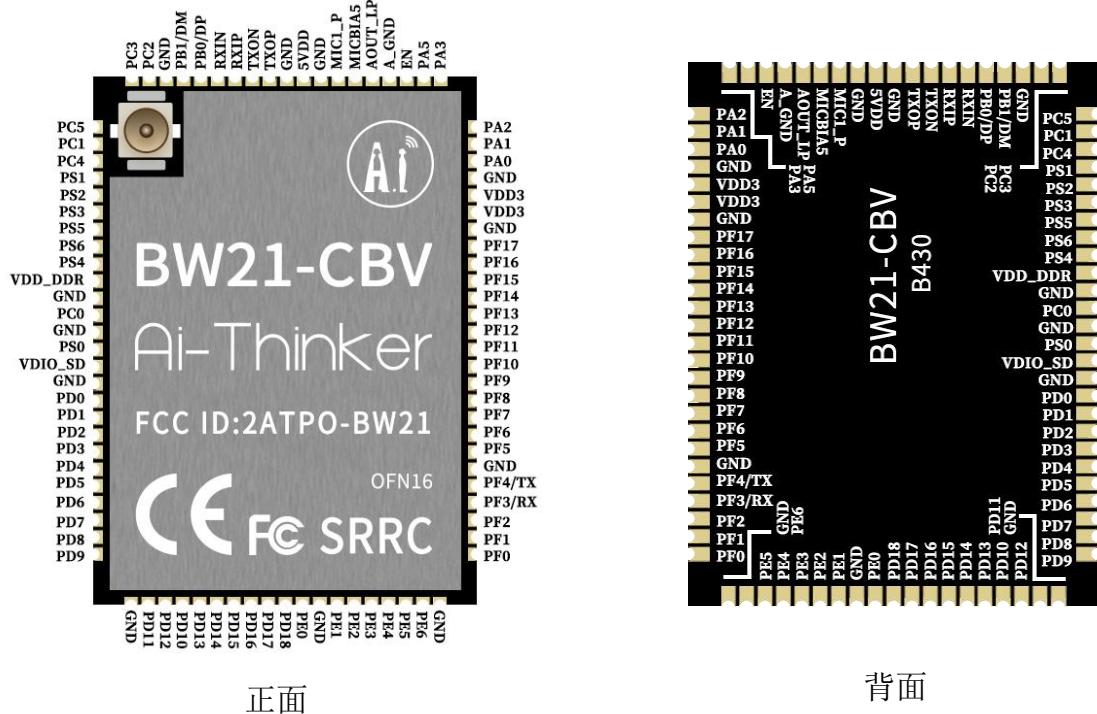
**Figure 4 Dimensions diagram**



**Figure 5 Shell cover information**

## 4. Pin Definition

The BW21-CBV module has a total of 90 pins, as shown in the pin diagram. The pin function definitions are shown in the table below.



**Figure 6 Schematic Diagram of Pin**

**Table 6 Definitions of pin function**

No	Name	Function Declaration
90	PC5	Default NC; GPIOC_5/FLASH_CS#
1	PC1	Default NC; GPIOC_1/FLASH_D3
2	PC4	Default NC; GPIOC_4/FLASH_D1
3	PS1	GPIOS_1/IO9/SD_D1/PWM8
4	PS2	GPIOS_2/IO80/SD_D0
5	PS3	GPIOS_3/IO81/SD_CMD
6	PS5	GPIOS_5/IO82/SD_D3/PWM10
7	PS6	GPIOS_6/IO12/SD_D2/PWM11
8	PS4	GPIOS_4/IO11/SD_CD/PWM9
9	VDD_DDR	DDR 2 power supply terminal, 1.8V input, external power supply output current is recommended to be above 500 mA

10	GND	Ground
11	PC0	Default NC; GPIOC_0/FLASH_CLK
12	GND	Ground
13	PS0	GPIOS_0/IO79/SD_CLK
14	VDIO_SD	The power supply terminal of GPIOS power domain is powered by the chip inside. When the SD card is used, it can be used as the resistance power supply for the SD card. in other cases
15	GND	Ground
16	PD0	GPIOD_0/IO83/MIPI_DATA0_P
17	PD1	GPIOD_1/IO13/MIPI_DATA0_N
18	PD2	GPIOD_2/IO84/MIPI_DATA1_P
19	PD3	GPIOD_3/IO14/MIPI_DATA1_N
20	PD4	GPIOD_4/IO85/MIPI_CK1_P
21	PD5	GPIOD_5/IO15/MIPI_CK1_N
22	PD6	GPIOD_6/IO86/MIPI_DATA2_P
23	PD7	GPIOD_7/IO16/MIPI_DATA2_N
24	PD8	GPIOD_8/IO17/MIPI_DATA3_P
25	PD9	GPIOD_9/IO17/MIPI_DATA3_N
26	GND	Ground
27	PD11	GPIOD_11/IO19/SSOR_PDN
28	PD12	GPIOD_12/IO21/I2C3_SCL
29	PD10	GPIOD_10/IO20/I2C3_SDA
30	PD13	GPIOD_13/IO88/SSOR_SYSCLK
31	PD14	GPIOD_14/IO89/DMIC_CLK/WIFI_LED/I2S1_CLK/BT_PRI
32	PD15	GPIOD_15/IO23/I2S1_SD_TX0/UART2_OUT/BT_STA
33	PD16	GPIOD_16/IO90/DMIC_CLK/I2S1_MCK/UART2_IN/BT_CK
34	PD17	GPIOD_17/IO24/RFE_CTRL_4/I2S1_WS/UART2_CTS/WL_ACT
35	PD18	GPIOD_18/IO91/DMIC_DATA/RFE_CTRL_5/I2S1_SD_RX/UART2_RTS/BTCMD_IRQ
36	PE0	GPIOE_0/IO92/SSOR_RST/WIFI_LED/RFE_CTRL_3/UART2_OUT
37	GND	Ground

38	PE1	GPIOE_1/IO93/SPI_0_SCL/SPI_2_SCL/UART3_OUT
39	PE2	GPIOE_2/IO94/SPI_0_MISO/SPI_2_MSIO/UART3_IN
40	PE3	GPIOE_3/IO28/I2C2_SCL/RFE_CTRL4/SPI_0_MOSI/SPI_2_MOSI/UART3_RTS
41	PE4	GPIOE_4/IO95/I2C_SDA/RFE_CTRL5/SPI_0_CS0/SPI_2_CS/UART3_CTS
42	PE5	GPIOE_5/IO29/I2C2_SCL/SPI_0_CS1
43	PE6	GPIOE_6/IO96/I2C2_SDA/SPI_0_CS2
44	GND	Ground
45	PF0	GPIOF_0/IO43/ADC0
46	PF1	GPIOF_1/IO106/ADC1/I2C1_SCL/RFE_CTRL_0/UART1_CTS
47	PF2	GPIOF_2/IO44/ADC2/I2C1_SDA/RFE_CTRL_1/UART1_RTS
48	PF3/RX	GPIOF_3/IO107/ADC3/RFE_CTRL_2/UART1_IN
49	PF4/TX	GPIOF_4/IO108/UART1_OUT
50	GND	Ground
51	PF5	GPIOF_5/IO46/SPI_1_MISO/SPI_3_MISO
52	PF6	GPIOF_6/IO109/PWM0/SPI_1_SCL/SPI_3_SCL
53	PF7	GPIOF_7/IO47/PWM1/SPI_1_MOSI/SPI_3_MOSI
54	PF8	GPIOF_8/IO110/PWM2/SPI_1_CS0/SPI_3_CS
55	PF9	GPIOF_9/IO111/SGPIO_RX/PWM3/SPI_1_CS1
56	PF10	GPIOF_10/IO49/PWM4/SPI_1_CS2

57	PF11	GPIOF_11/IO112/PWM5/I2S0_MCK
58	PF12	GPIOF_12/IO50/PWM6/I2S0_SD_RX/UART1_IN
59	PF13	GPIOF_13/IO113/PWM7/I2S0_CLK/UART1_OUT
60	PF14	GPIOF_14/IO114/SGPIO_RX/PWM8/I2S0_SD_TX0
61	PF15	GPIOF_15/IO52/SGPIO_TX/PWM9/I2S_WS
62	PF16	GPIOF_16/IO53/PWM10/SPI_1_CS3
63	PF17	GPIOF_17/IO54/VDD_DDR_EN/PWM11, DDR power enable pin
64	GND	Ground
65	VDD3	3.3V power supply pin, the output current of the external power supply is recommended to be above 700 mA
66	VDD3	3.3V power supply pin, the output current of the external power supply is recommended to be above 700 mA
67	GND	Ground
68	PA0	GPIOA_0/IO117/ADC4/XTAL_XO_32/I2C0_SCL,32K crystal vibration output pin
69	PA1	GPIOA_1/IO59/ADC5/XTAL_XI_32/I2C0_SDA, 32Kcrystal vibration output pin
70	PA2	GPIOA_2/IO118/ADC6/UART0_OUT
71	PA3	GPIOA_3/IO60/ADC7/UART0_IN
72	PA5	GPIOA_5/IO120/SSOR_PWR_CTRL, Camera Sensor power control pin, pull up effective, module default pull down 100K resistance
73	EN	CHIP_EN, the chip enable pin, pull up Enable; pull down shutdown.10K resistance inside the module
74	A_GND	AUDIO_GND, Audio simulation
75	AOUT_LP	AOUT_LP, The speaker output a positive signal

76	MICBIAS	MICBIAS, MIC offset output
77	MIC1_P	MIC1_P, MIC enter a positive signal
78	GND	Ground
79	5VDD	5V power supply pin, the output current of the external power supply is recommended to be above 500 mA
80	GND	Ground
81	TXOP	EPHY_TXOP; Ethernet TX+
82	TXON	EPHY_TXON; Ethernet TX-
83	RXIP	EPHY_RXIP; Ethernet RX+
84	RXIN	EPHY_RXIN; Ethernet RX+
85	PB0/DP	GPIOB_0/IO70/I2C0_SCL/HSDP, High-speed USB D + signal
86	PB1/DM	GPIOB_1/IO71/I2C0_SDA/HSDM, High-speed USB D + signal
87	GND	Ground
88	PC2	Default NC; GPIOC_2/FLASH_D0#
89	PC3	Default NC; GPIOC_3/FLASH_D2#

Note: 1. When the power moment of PA5 is high level, the module enters the burning mode; when the power moment is low level, the module starts normally, and the internal pull-down by default.

2. PC0, PC1, PC2, PC3, PC4 and PC5 are internal FLASH pins in the module, which are not available by default and are suspended.

## 5. Design Guidance

### 5.1. Application circuit guidance

- GPIOA\_5 is the starting control foot, in normal operating mode at low level and burning firmware mode at high level. The default pull-down resistance is 100K.
- The module pin 9 VDD\_DDR is built DDR 2 power pin, which must be connected to 1.8V power supply; module 79 pin 5 VDD must be connected to 5V power supply; module 65 and 66 pins VDD 3, please use 3.3V current greater than 700 mA power supply. The four power pins must supply power normally, otherwise the module cannot start normally.

## 5.2. Recommend for PCB package size

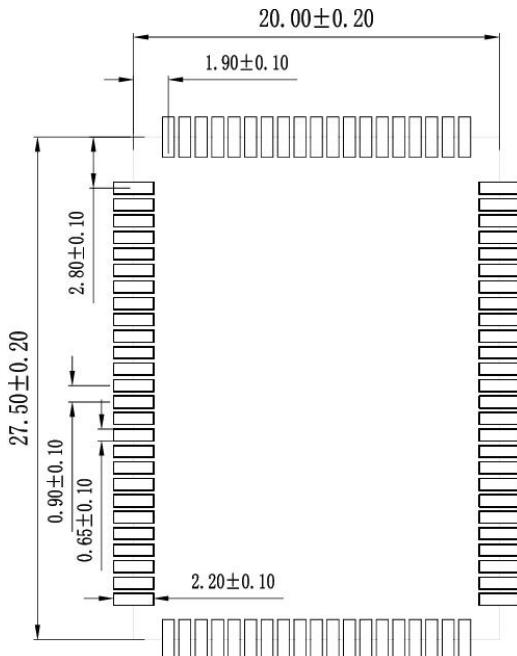


Figure 10 Recommend PCB package size (TOP view)

## 5.3. Antenna layout requirements

- The module requires use an external antenna.
- In order to satisfy the performance of the antenna, metal parts are prohibited around the antenna away from high frequency devices.

## 5.4. Power supply

- Recommended 3.3V voltage, peak current above 700 mA.
- It is recommended to use LDO power supply; if use DC-DC, suggest ripple wave within 100 mV.
- The DC-DC power supply circuit suggests to reserve the position of the dynamic response capacitor, which can optimize the output ripple when the load change is large.
- In the 3.3V power interface, it is recommended to add ESD devices.
- If the power supply is boosted from 1.5V to 3.0V for more than 15 ms, increase the voltage reset IC.
- During the repeated power on-off process, if the voltage cannot be guaranteed to be less than 0.3V, the voltage reset IC must be increased.

## 5.5. GPIO

- The periphery of the module pin outs some IO ports, If you need to use them, it is recommended to connect a 10-100 ohm resistor in series to the IO ports. This can suppress the overshoot and make the level on both sides more stable, it helps both for EMI and ESD
- Pull up and down of the special IO port, refer to the instructions of the specification, which will affect the startup configuration of the module.
- The IO port of the module is 3.3V. If the main control does not match the IO port level of the module, the level conversion circuit should be added.
- If the IO port is directly connected to the peripheral interface or terminals, it is recommended to reserve ESD devices at the IO port line near the terminal.

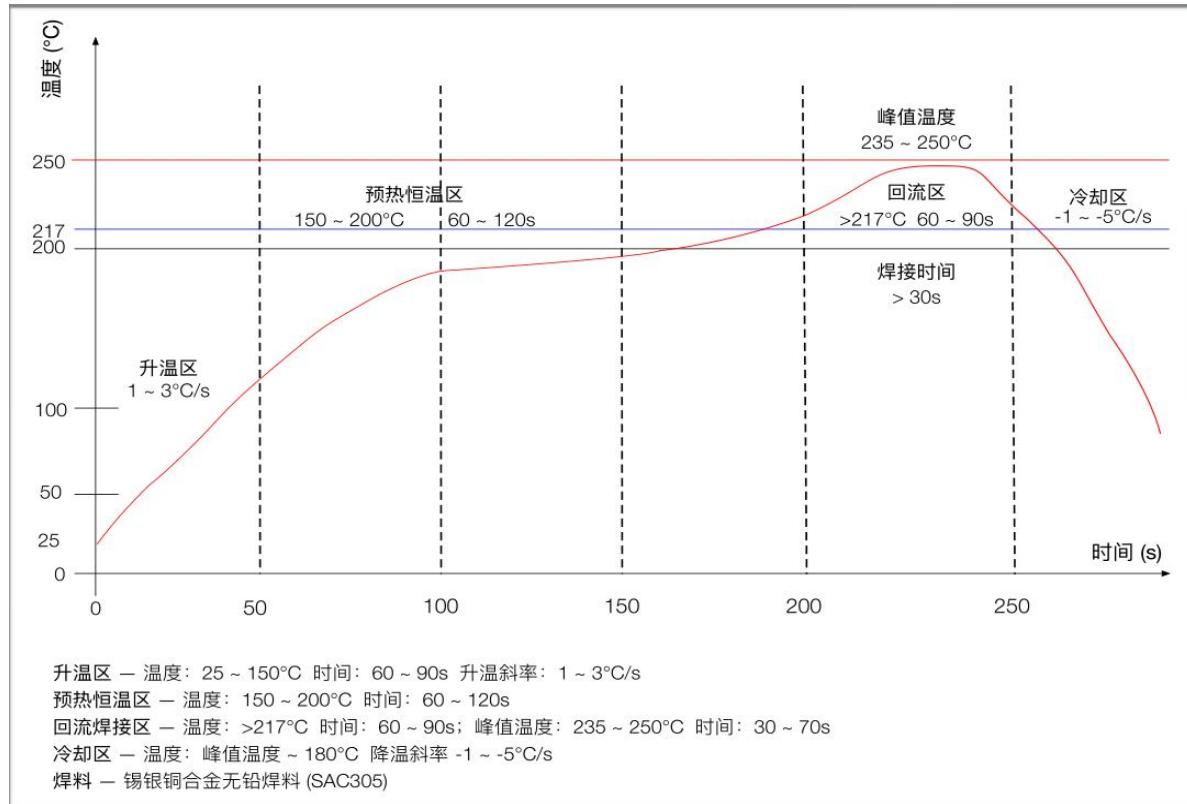
## 6. Storage Condition

Products sealed in a moisture-proof bag shall be stored in a non-condensing atmosphere of <40°C / 90% RH.

The moisture sensitivity grade MSL of the module is level 3.

After the vacuum bag is unsealed, it must be used within 168 hours at  $25 \pm 5^\circ\text{C} / 60\% \text{ RH}$ , otherwise it needs to be baked before the production.

## 7. Reflow Welding Curve Diagram



## 8. Product Packaging Information

BW21-CBV module is packaged at 700 pcs /tape. As shown in the figure below:



Figure 14 Tape packaging diagram

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## FCC WARNING

FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

This device complies with Part 15 of the FCC Rules.

Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

This device and its antenna(s) must not be co-located or operating in conjunction with any other antenna or transmitter.

### 15.105 Information to the user.

(b) For a Class B digital device or peripheral, the instructions furnished the user shall include the following or similar statement, placed in a prominent location in the text of the manual:

Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules.

These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

—Reorient or relocate the receiving antenna.

—Increase the separation between the equipment and receiver.

—Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.

—Consult the dealer or an experienced radio/TV technician for help.

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator and your body. Radiation Exposure Statement:

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment.

This transmitter must not be co-located or operating in conjunction with any other

antenna or transmitter.

The availability of some specific channels and/or operational frequency bands are country dependent and are firmware programmed at the factory to match the intended destination.

The firmware setting is not accessible by the end user.

The final end product must be labelled in a visible area with the following:

“Contains Transmitter Module “FCC ID: 2ATPO-BW21”

## Requirement per KDB996369 D03

### 2.2 List of applicable FCC rules

List the FCC rules that are applicable to the modular transmitter. These are the rules that specifically establish the bands of operation, the power, spurious emissions, and operating fundamental frequencies. DO NOT list compliance to unintentional-radiator rules (Part 15 Subpart B) since that is not a condition of a module grant that is extended to a host manufacturer. See alsoSection 2.10 below concerning the need to notify host manufacturers that further testing is required.3

**Explanation:** This module meets the requirements of FCC part 15C (15.247).it Specifically identified AC Power Line Conducted Emission, Radiated Spurious emissions, Band edge and RF Conducted Spurious Emissions, Conducted Peak Output Power, Bandwidth, Power Spectral Density, Antenna Requirement.

### 2.3 Summarize the specific operational use conditions

Describe use conditions that are applicable to the modular transmitter, including for example any limits on antennas, etc. For example, if point-to-point antennas are used that require reduction in power or compensation for cable loss, then this information must be in the instructions. If the use condition limitations extend to professional users, then instructions must state that this information also extends to the host manufacturer's instruction manual. In addition, certain information may also be needed, such as peak gain per frequency band and minimum gain, specifically for master devices in 5 GHz DFS bands.

**Explanation:** The product antenna uses an irreplaceable antenna with a gain of Bluetooth: 3.39dBi, WiFi (2.4G): 3.39dBi, WiFi (5.2G): 3.17dBi, WiFi (5.3G): 3.42dBi, WiFi (5.6G): 2.66dBi, WiFi (5.8G): 3.03dBi

### 2.4 Single Modular

If a modular transmitter is approved as a “Single Modular,” then the module manufacturer is responsible for approving the host environment that the Single Modular is used with. The manufacturer of a Single Modular must describe, both in the filing and in the installation instructions, the alternative means that the Single Modular manufacturer uses to verify that the host meets the necessary requirements to satisfy the module limiting conditions. A Single Modular manufacturer has the flexibility to define its alternative method to address the conditions that limit the initial approval, such as: shielding, minimum signaling amplitude, buffered modulation/data inputs, or power supply regulation. The alternative method could include that the limited

module manufacturer reviews detailed test data or host designs prior to giving the host manufacturer approval.

This Single Modular procedure is also applicable for RF exposure evaluation when it is necessary to demonstrate compliance in a specific host. The module manufacturer must state how control of the product into which the modular transmitter will be installed will be maintained such that full compliance of the product is always ensured. For additional hosts other than the specific host originally granted with a limited

module, a Class II permissive change is required on the module grant to register the additional host as a specific host also approved with the module.

**Explanation:** The module is a single module.

## 2.5 Trace antenna designs

For a modular transmitter with trace antenna designs, see the guidance in Question 11 of KDB Publication 996369 D02 FAQ – Modules for Micro-Strip Antennas and traces. The integration information shall include for the TCB review the integration instructions for the following aspects: layout of trace design, parts list (BOM), antenna, connectors, and isolation requirements.

a) Information that includes permitted variances (e.g., trace boundary limits, thickness, length, width, shape(s), dielectric constant, and impedance as applicable for each type of antenna); b) Each design shall be considered a different type (e.g., antenna length in multiple(s) of frequency, the wavelength, and antenna shape (traces in phase) can affect antenna gain and must be considered); c) The parameters shall be provided in a manner permitting host manufacturers to design the printed circuit (PC) board layout; d) Appropriate parts by manufacturer and specifications; e) Test procedures for design verification; and f) Production test procedures for ensuring compliance

The module grantee shall provide a notice that any deviation(s) from the defined parameters of the antenna trace, as described by the instructions, require that the host product manufacturer must notify the module grantee that they wish to change the antenna trace design. In this case, a Class II permissive change application is required to be filed by the grantee, or the host manufacturer can take responsibility through the change in FCC ID (new application) procedure followed by a Class II permissive change application

## 2.6 RF exposure considerations

It is essential for module grantees to clearly and explicitly state the RF exposure conditions that permit a host product manufacturer to use the module. Two types of instructions are required for RF exposure information: (1) to the host product manufacturer, to define the application conditions (mobile, portable – xx cm from a person's body); and (2) additional text needed

for the host product manufacturer to provide to end users in their end-product manuals. If RF exposure statements and use conditions are not provided, then the host product manufacturer is required to take responsibility of the module through a change in FCC ID (new application).

**Explanation:** The module complies with FCC radiofrequency radiation exposure limits for uncontrolled environments. The device is installed and operated with a distance of more than 20 cm between the radiator and your body." This module follows FCC statement design, FCC ID : 2ATPO-BW21

## 2.7 Antennas

A list of antennas included in the application for certification must be provided in the instructions. For modular transmitters approved as limited modules, all applicable professional installer instructions must be included as part of the information to the host product manufacturer. The antenna list shall also identify the antenna types (monopole, PIFA, dipole, etc. (note that for example an "omni-directional antenna" is not considered to be a specific "antenna type").

For situations where the host product manufacturer is responsible for an external connector, for example with an RF pin and antenna trace design, the integration instructions shall inform the installer that unique antenna connector must be used on the Part 15 authorized transmitters used in the host product.

The module manufacturers shall provide a list of acceptable unique connectors.

**Explanation:** The product antenna uses an irreplaceable antenna with a gain of Bluetooth: 3.39dBi, WiFi (2.4G): 3.39dBi, WiFi (5.2G): 3.17dBi, WiFi (5.3G): 3.42dBi, WiFi (5.6G): 2.66dBi, WiFi (5.8G): 3.03dBi

## 2.8 Label and compliance information

Grantees are responsible for the continued compliance of their modules to the FCC rules. This

includes advising host product manufacturers that they need to provide a physical or e-label stating "Contains FCC ID" with their finished product. See Guidelines for Labeling and User Information for RF Devices – KDB Publication 784748.

**Explanation:** The host system using this module, should have label in a visible area indicated the following texts: "Contains FCC ID: 2ATPO-BW21

## 2.9 Information on test modes and additional testing requirements<sup>5</sup>

Additional guidance for testing host products is given in KDB Publication 996369 D04 Module Integration Guide. Test modes should take into consideration different operational conditions for a stand-alone modular transmitter in a host, as well as for multiple simultaneously transmitting modules or other transmitters in a host product.

The grantee should provide information on how to configure test modes for host product evaluation for different operational conditions for a stand-alone modular transmitter in a host, versus with multiple, simultaneously transmitting modules or other transmitters in a host.

Grantees can increase the utility of their modular transmitters by providing special means, modes, or instructions that simulates or characterizes a connection by enabling a transmitter. This can greatly simplify a host manufacturer's determination that a module as installed in a host complies with FCC requirements.

**Explanation:** Shenzhen Ai-Thinker Technology Co., Ltd can increase the utility of our modular transmitters by providing instructions that simulates or characterizes a connection by enabling a transmitter.

## 2.10 Additional testing, Part 15 Subpart B disclaimer

The grantee should include a statement that the modular transmitter is only FCC authorized for the specific rule parts (i.e., FCC transmitter rules) listed on the grant, and that the host product manufacturer is responsible for compliance to any other FCC rules that apply to the host not covered by the modular transmitter grant of certification. If the grantee markets their product

as being Part 15

Subpart B compliant (when it also contains unintentional-radiator digital circuitry), then the grantee shall provide a notice stating that the final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed.

**Explanation:** The module without unintentional-radiator digital circuitry, so the module does not require an evaluation by FCC Part 15 Subpart B. The host should be evaluated by the FCC Subpart B.